

# Table of Contents



**Sony  
IMX157  
CMOS Image Sensor  
from the SLT-A99 ( $\alpha$ 99) Full-Frame  
Interchangeable Lens Camera**

**Imager Process Review**

**Sony IMX157**  
**CMOS Image Sensor**  
Imager Process Review

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## Table of Contents

### **1 Overview**

- 1.1 List of Figures
- 1.2 List of Tables
- 1.3 Company Profile
- 1.4 Introduction
- 1.5 Device Summary
- 1.6 Process Summary

### **2 Device Overview**

- 2.1 Downstream Product
- 2.2 Package and Die
- 2.3 Die Features

### **3 Process Analysis**

- 3.1 General Device Structure
- 3.2 Bond Pads
- 3.3 Dielectrics
- 3.4 Metallization
- 3.5 Vias and Contacts
- 3.6 Transistors and Poly
- 3.7 Isolation
- 3.8 Wells and Substrate

### **4 Pixel Analysis**

- 4.1 Pixel Overview and Schematic
- 4.2 Pixel Plan-View Analysis
- 4.3 Edge Pixel and Phase-Detection Pixel Analysis
- 4.4 Pixel Array Cross Section – Parallel to Column Out Line
- 4.5 Pixel Array Cross Section – Parallel to Row Select Line

### **5 Critical Dimensions**

- 5.1 Die Features
- 5.2 Dielectrics
- 5.3 Metallization
- 5.4 Vias and Contacts
- 5.5 Transistors and Poly
- 5.6 Isolation
- 5.7 Wells and Substrate
- 5.8 Pixel Plan-View Analysis
- 5.9 Pixel Array Cross Section – Parallel to Column Out Line

**6 References**

**7 Statement of Measurement Uncertainty and Scope Variation**

**About Chipworks**

## 1 Overview

### 1.1 List of Figures

#### **2 Device Overview**

- 2.1.1 Sony  $\alpha$ 99
- 2.2.1 Image Sensor Package – Front
- 2.2.2 Image Sensor Package – Back, PWB Intact
- 2.2.3 Image Sensor Package – Back, PWB Removed
- 2.2.4 Image Sensor Package X-Ray
- 2.2.5 Image Sensor Package X-Ray, Detail
- 2.2.6 Image Sensor Package – Side View
- 2.2.7 Image Sensor Package – Side View, Detail
- 2.2.8 Image Sensor Package – Side View X-Ray
- 2.2.9 Image Sensor Die Photograph
- 2.2.10 Die Markings A
- 2.2.11 Die Markings B
- 2.2.12 Die Markings C
- 2.2.13 Analysis Sites
- 2.3.1 Die Corner A
- 2.3.2 Die Corner B
- 2.3.3 Die Corner C
- 2.3.4 Die Corner D
- 2.3.5 Bond Pad Pitch
- 2.3.6 Test Pad Pitch
- 2.3.7 Active Pixel Array – Corner A
- 2.3.8 Active Pixel Array – Corner B
- 2.3.9 Active Pixel Array – Corner C
- 2.3.10 Active Pixel Array – Corner D
- 2.3.11 Color Filter Array – Detail
- 2.3.12 Die Feature A
- 2.3.13 Die Feature B
- 2.3.14 Die Feature C
- 2.3.15 Die Feature D
- 2.3.16 Die Feature E
- 2.3.17 Die Feature F
- 2.3.18 Die Feature G

#### **3 Process Analysis**

- 3.1.1 Die Thickness
- 3.1.2 Die Seal
- 3.1.3 General Structure – Periphery
- 3.1.4 General Structure – Pixel Array
- 3.2.1 Bond Pad Edge – Left
- 3.2.2 Bond Pad Edge – Right
- 3.3.1 Passivation
- 3.3.2 Passivation – TEM

- 3.3.3 IMD 2
- 3.3.4 IMD 1
- 3.3.5 PMD – Peripheral Region
- 3.3.6 PMD – TEM
- 3.4.1 Minimum Pitch Metal 3
- 3.4.2 Metal 3 – TEM
- 3.4.3 Minimum Pitch Metal 2 – TEM
- 3.4.4 Minimum Pitch Metal 1
- 3.4.5 Metal 1 – TEM
- 3.5.1 Minimum Pitch Via 1s and 2s
- 3.5.2 Contact to Poly – TEM
- 3.5.3 Contact to Silicided Diffusion
- 3.5.4 Contact to Silicide Interface – TEM
- 3.6.1 Minimum Contacted Logic Gate Pitch
- 3.6.2 Logic Transistor Gate Overview – TEM
- 3.6.3 Logic Transistor Gate Dielectric – TEM
- 3.6.4 PMOS Logic Transistors – Si Etch
- 3.7.1 LOCOS – Logic Region
- 3.8.1 Die Edge Well and Substrate Overview – Si Etch
- 3.8.2 Peripheral Region Well and Substrate Overview – Si Etch
- 3.8.3 Peripheral Region Well and Substrate Overview – SCM
- 3.8.4 Peripheral Region Embedded N-Well – Si Etch
- 3.8.5 SRP Analysis Sites (Location 1)
- 3.8.6 SRP Analysis Sites (Locations 2 and 3)
- 3.8.7 SRP Profile – Location 1
- 3.8.8 SRP Profile – Location 2
- 3.8.9 SRP Profile – Location 3
- 4 Pixel Analysis**
- 4.1.1 Pixel Schematic
- 4.2.1 Microlenses – Tilt View
- 4.2.2 Microlens – Tilt View, Detail
- 4.2.3 Microlenses – Plan View
- 4.2.4 RGB Bayer Patterned Color Filter Array
- 4.2.5 Shared Pixels at Metal 3
- 4.2.6 Shared Pixels at Metal 2
- 4.2.7 Shared Pixels at Metal 1
- 4.2.8 Shared Pixels at Poly
- 4.2.9 Shared Pixels at Diffusion
- 4.2.10 Pixel Transfer Gate at Diffusion
- 4.2.11 Bevel SCM of Pixels
- 4.3.1 Bevel Sample Overview
- 4.3.2 Top Edge Dark Pixels
- 4.3.3 Left Edge Dark Pixels
- 4.3.4 Left Edge Metal 3 Alignment
- 4.3.5 Phase Detection Pixel Overview

- 4.3.6 Phase Detection Pixel Rows
- 4.3.7 Phase Detection Pixel – Region A
- 4.3.8 Phase Detection Pixels – Region A, Detail
- 4.3.9 Phase Detection Pixels – Region B
- 4.3.10 Phase Detection Pixels – Region C
- 4.3.11 Phase Detection Pixels – Region D
- 4.4.1 Start of RGB Color Filter Array
- 4.4.2 Periphery to Dark Pixel Transition
- 4.4.3 Dark Pixel to Active Pixel Transition
- 4.4.4 T1 and T2 Transistor – Oxide Etch
- 4.4.5 T1 and T2 Transistor – Silicon Etch
- 4.4.6 Photocathode Overview
- 4.4.7 SCM of Photocathodes
- 4.4.8 TEM of Transfer Gate
- 4.4.9 TEM of Transfer Gate – Source Region
- 4.4.10 TEM of Transfer Gate – Drain Region
- 4.4.11 TEM of Transfer Gate Dielectric
- 4.4.12 T3 Transistor – Oxide Etch
- 4.4.13 TEM of Gate Wrap
- 4.4.14 T5 Transistor – Oxide Etch
- 4.4.15 T6 Transistor – Oxide Etch
- 4.4.16 Phase Detection Pixel Overview
- 4.4.17 Phase Detection Pixel
- 4.4.18 Phase Detection Pixel Overview – Silicon Etch
- 4.5.1 Edge Pixels
- 4.5.2 T3 Transistor – Si Etch
- 4.5.3 T4, T5, and T6 Transistors – Si Etch
- 4.5.4 Red Filter
- 4.5.5 Green Filter
- 4.5.6 Blue Filter

## 1.2 List of Tables

### **1 Overview**

- 1.4.1 Device Identification
- 1.5.1 Device Summary
- 1.6.1 IMX157 Process Summary

### **2 Device Overview**

- 2.3.1 Die, Bond Pad, and Standard Cell Dimensions

### **3 Process Analysis**

- 3.3.1 Measured Dielectric Thicknesses
- 3.4.1 Metallization Thicknesses
- 3.4.2 Metallization Width and Pitch
- 3.5.1 Via and Contact Dimensions
- 3.6.1 Logic Transistor and Poly Dimensions
- 3.7.1 LOCOS Critical Dimensions
- 3.8.1 Well Depths and Die Thickness

### **4 Pixel Analysis**

- 4.2.1 Pixel Horizontal Dimensions
- 4.4.1 Pixel Vertical Dimensions
- 4.4.2 Pixel Transistor Gate Physical Dimensions

### **5 Critical Dimensions**

- 5.1.1 Die, Bond Pad, and Standard Cell Dimensions
- 5.2.1 Measured Dielectric Thicknesses
- 5.3.1 Metallization Thicknesses
- 5.3.2 Metallization Width and Pitch
- 5.4.1 Via and Contact Dimensions
- 5.5.1 Logic Transistor and Poly Dimensions
- 5.6.1 LOCOS Critical Dimensions
- 5.7.1 Well Depths and Die Thickness
- 5.8.1 Pixel Horizontal Dimensions
- 5.9.1 Pixel Vertical Dimensions
- 5.9.2 Pixel Transistor Gate Physical Dimensions



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